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Applicant Number	09/678,414
Filing Date	October 2, 2000
First Named Inventor	David W. Carlson
Group Art Unit	2823
Examiner Name	B. Kebede
Attorney Docket Number	100-13600 (P04797)

Total Number of Pages in This Submission 11

ENCLOSURES (check all that apply)

- ☐ Fee Transmittal Form
- ☐ Fee Attached
- ☒ Amendment/Response to Paper No. 7
- ☒ After Final (Response)
- ☐ Affidavits/declaration(s)
- ☐ Extension of Time Request
- ☐ Express Abandonment Request
- ☐ Information Disclosure Statement
- ☐ Certified Copy of Priority Document(s)
- ☐ Response to Missing Parts/Incomplete Application
- ☐ Response to Missing Parts under 37 CFR 1.52 or 1.53

- ☐ Assignment Papers (for an Application)
- ☐ Drawing(s)
- ☐ Licensing-related Papers
- ☐ Petition Routing Slip (PTO/SB/69) and Accompanying Petition
- ☐ Petition to Convert to a Provisional Application
- ☐ Power of Attorney, Revocation Change of Correspondence Address
- ☐ Terminal Disclaimer
- ☐ Request for Refund
- ☐ CD, Number of CD(s) _____

- ☐ After Allowance Communication to Group
- ☐ Appeal Communication to Board of Appeals and Interferences
- ☐ Appeal Communication to Group (Appeal Notice, Brief, Reply Brief)
- ☐ Proprietary Information
- ☐ Status Inquiry

- ☒ Other Enclosure(s)
(please identify below):

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Mark C. Pickering, Reg. No. 36,239

Signature

Date

August 5, 2002

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Typed or printed name

Robin L. King

Signature

Date

August 5, 2002

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TO IPE
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09/678,414
Response to Office Action Mailed June 5, 2002

COPY OF PAPERS
ORIGINALLY FILED

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:

David W. Carlson ✓

Appln. No.: 09/678,414 ✓

Filed: October 2, 2000

For: METHOD FOR PLANARIZING A THIN
FILM

Group Art Unit: 2823

Examiner: B. Kebede

RESPONSE TO OFFICE ACTION MAILED
JUNE 5, 2002

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Commissioner for Patents
Washington, D.C. 20231

#10/B
Amend
N/E
JmCimella
8/22/02

Dear Sir:

In response to the Official Action mailed June 5, 2002, please amend the above-
identified application as follows:

In the Claims

Claim 18 has been cancelled.

The claims have been amended to read as follows:

16. (Amended) The method of claim 1 wherein the layer of first material makes
an electrical contact with a device on the wafer.

19. (Amended) The method of claim 22 wherein the first lower level lies above
the wafer upper level.

20. (Amended) The method of claim 19
wherein the planarized layer of first material has a thickness over the wafer upper
layer, and

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